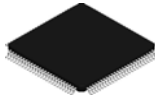


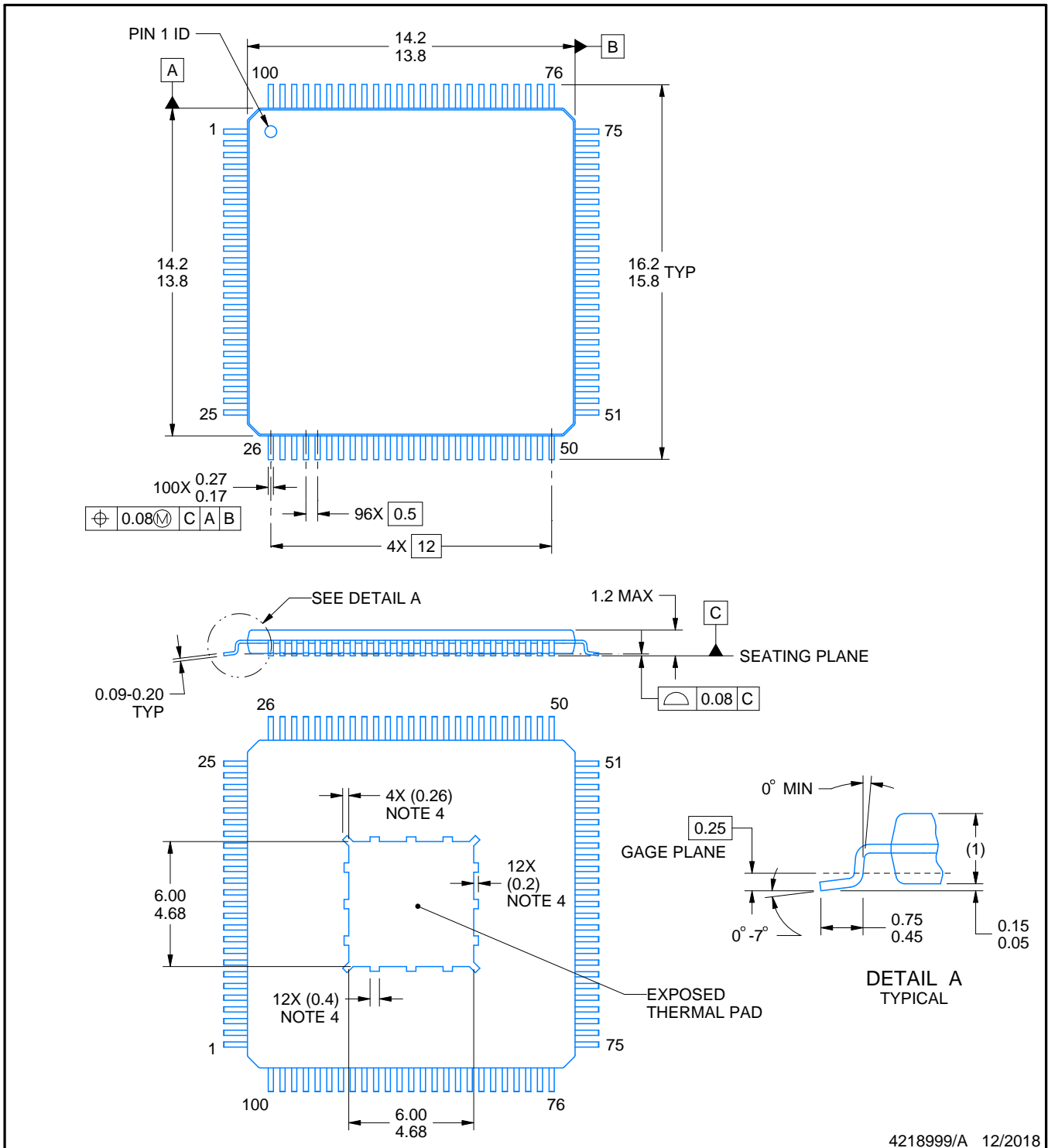
# PZP0100K



# PACKAGE OUTLINE

PowerPAD™ TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



4218999/A 12/2018

## NOTES:

PowerPAD is a trademark of Texas Instruments.

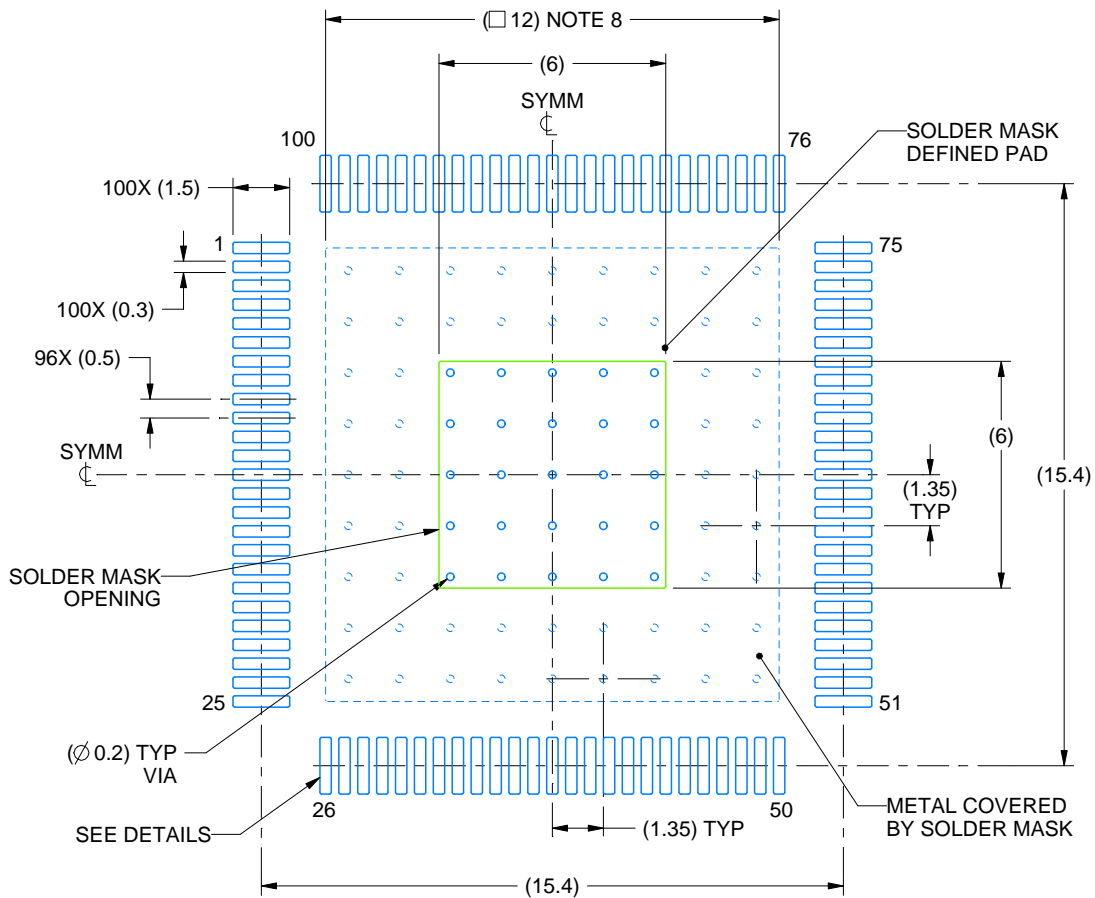
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Reference JEDEC registration MS-026, variation ACD.
- Strap features may not be present.

# EXAMPLE BOARD LAYOUT

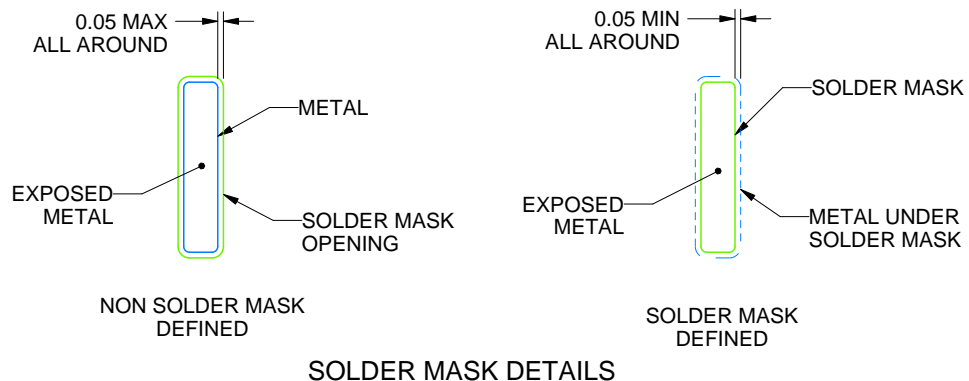
PZP0100K

PowerPAD™ TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:5X



SOLDER MASK DETAILS

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NOTES: (continued)

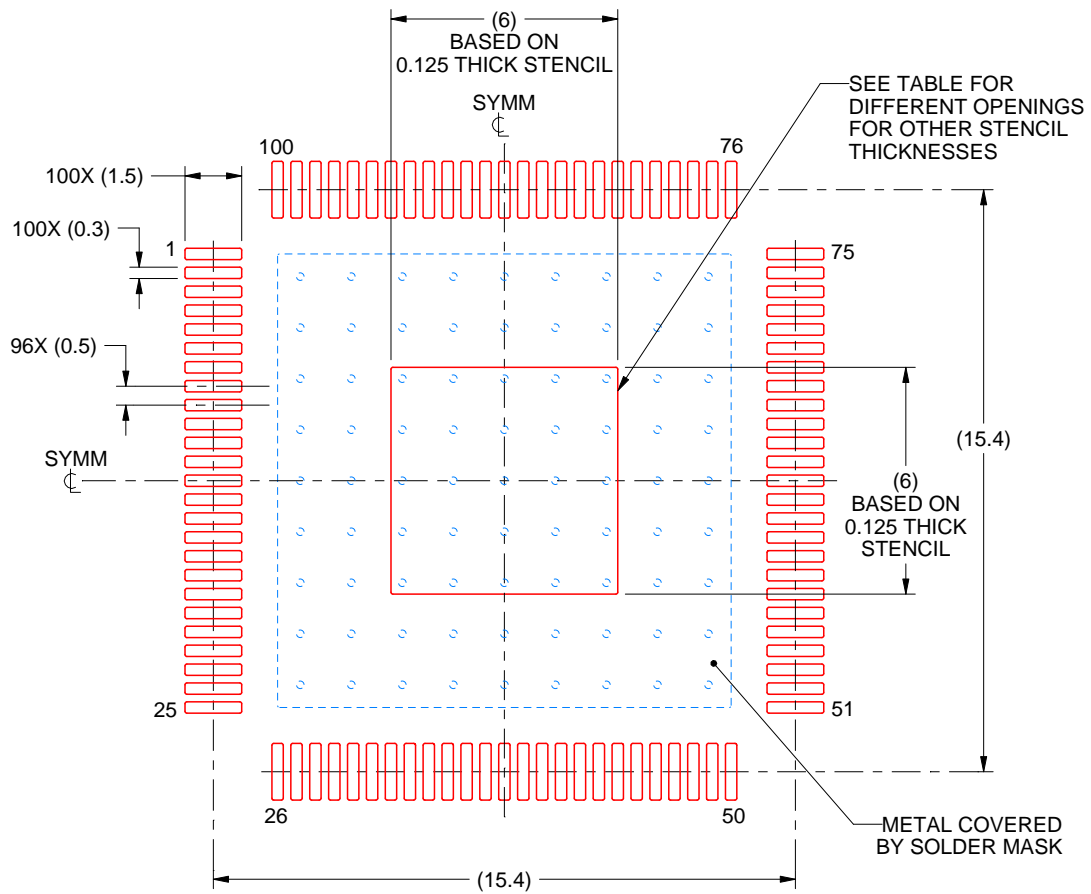
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
8. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

PZP0100K

PowerPAD™ TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



**SOLDER PASTE EXAMPLE**  
 EXPOSED PAD  
 100% PRINTED SOLDER COVERAGE BY AREA  
 SCALE:5X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	6.71 X 6.71
0.125	6 X 6 (SHOWN)
0.150	5.48 X 5.48
0.175	5.07 X 5.07

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NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- Board assembly site may have different recommendations for stencil design.

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